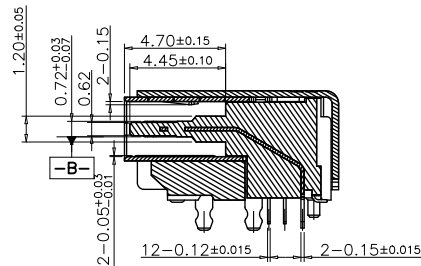
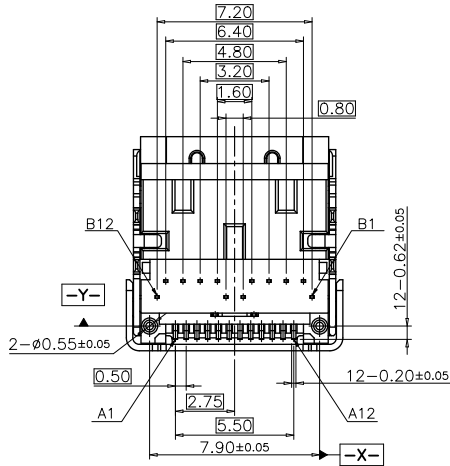
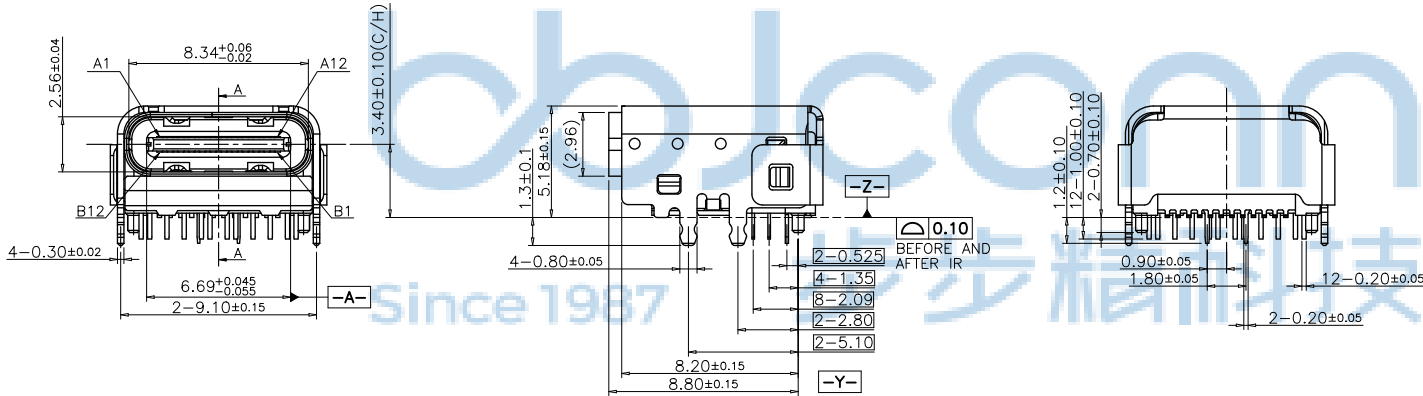
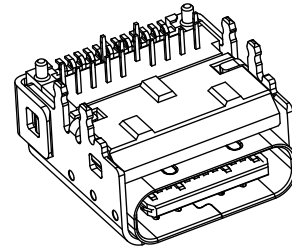
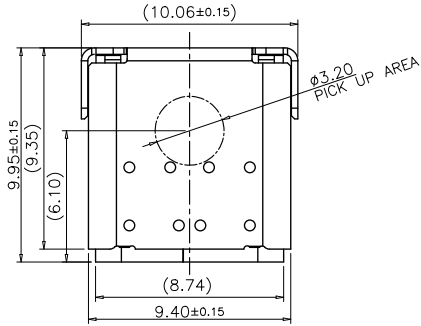


REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF

NOTES:

- ELECTRICAL CHARACTERIST;
 - CURRENT RATING:
 - 5A FOR VBUS (A4,A9,B4,B9)
 - 1.25A FOR VCONN PIN (B5), WITH RETURN PATH THROUGH THE CORRESPONDING GND PIN (A1,A12,B1,B12)
 - 0.5A FOR ALL OTHER PIN
 - CONTACT RESISTANCE(INITIAL): 40 mohms MAX; AFTER TEST: CHANGGE OF +10 mohms MAX;
 - INSULATION RESISTANCE: 100M ohms MIN;
 - DIELECTRIC WITHSTANDING VOLTAGE: 100V AC R.M.S FOR 1 MINUTE.
- MECHANICAL CHARACTERIST;
 - MATING DURABILITY: 10000 CYCLES;
 - MATING FORCE: 5~20N MAX;
 - UNMATING FORCE: 8~20N MIN BEFORE TEST; 6~20N AFTER TEST.
- ENVIRONMENTAL:
 - OPERATION TEMPERATURE: -55° TO +85°
- HARMFUL MATERIAL CONTROL PLEASE FOLLOW DOC.NO."LJ-QW-030", SHOULD BE COMPLIANCE TO REQUIREMENT ABOUT HF&RoHS&REACH.



SECTION A-A

Item	PART NAME	QTY	Material	Treatment
6	SPACER	1	Thermoplastic	Black,UL94-V0
5	CONTACT	1	Copper alloy	Ni plating on the soldering area Au 3U plating on contact area Au plating on soldering area
4	I/M HOUSING	1	Thermoplastic	Black,UL94-V0
3	PLATE	1	SUS301	Ni plating on the soldering area
2	MAIN-SHELL	1	SUS	Black Ni plating over all
1	OUT-SHELL	1	SUS	Ni plating on the soldering area

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PDWG:NO: 0627-1

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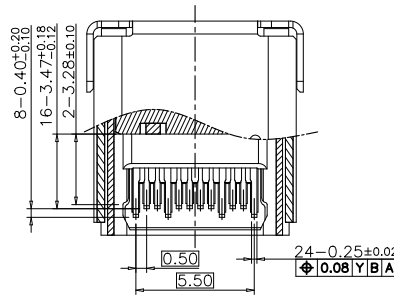
NAME: TYPE-C 24P 母座 四脚插 双壳 DIP脚长 1.2+SMT 脚距2.3 L=9.95 CH=3.4 镀金3U 编带

PJ. NO.: Δ126-223-240002-J4G
SIZE: A4 | DRW NO.:

FINISH: SEE NOTES | MAT'L.: SEE NOTES

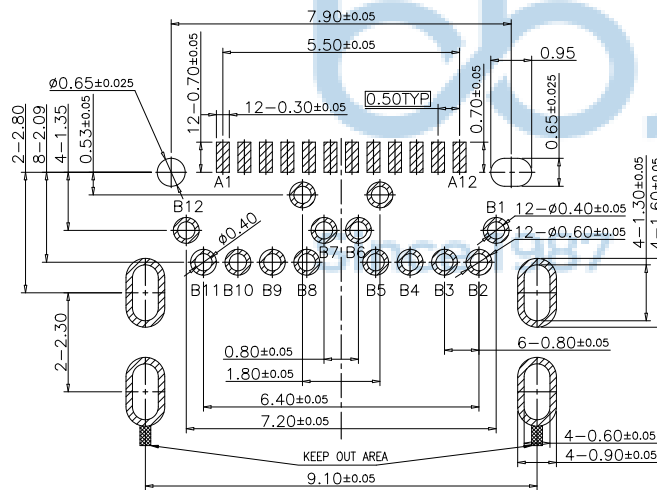
SCALE: N/A | REV.: A0 | UNIT: mm | PAGE: 1/2

APPD.: JM_Zheng
CHKD.: LYX
DR.: SGF



PIN DEFINE:

Pin	Signal Name	Description	Mating Sequence	Pin	Signal Name	Description	Mating Sequence
A1	GND	Ground return	First	B12	GND	Ground return	First
A2	SSTXp1	Positive half of first SuperSpeed TX differential pair	Second	B11	SSRXp1	Positive half of first SuperSpeed RX differential pair	Second
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	Second	B10	SSRXn1	Negative half of first SuperSpeed RX differential pair	Second
A4	Vbus	Bus Power	First	B9	Vbus	Bus Power	First
A5	CC1	Configuration Channel	Second	B8	SBU2	Sideband Use(SBU)	Second
A6	Dp1	Positive half of the USB 2.0 differential pair—Position 1	Second	B7	Dn2	Negative half of the USB 2.0 differential pair—Position 2	Second
A7	Dn1	Negative half of the USB 2.0 differential pair—Position 1	Second	B6	Dp2	Positive half of the USB 2.0 differential pair—Position 2	Second
A8	SBU1	Sideband Use(SBU)	Second	B5	CC2	Configuration Channel	Second
A9	Vbus	Bus Power	First	B4	Vbus	Bus Power	First
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	Second	B3	SSTXn2	Negative half of second SuperSpeed TX differential pair	Second
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	Second	B2	SSTXp2	Positive half of second SuperSpeed TX differential pair	Second
A12	GND	Ground return	First	B1	GND	Ground return	First



RECOMMENDED PCB PAD LAYOUT THICKNESS=1.20mm
TOLERANCE:0.05mm



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PDWG.NO: 0627-1	DR. SGF	.X: ±0.38 .XX: ±0.25 .XXX: ±0.13 X*: ±3* .X*: ±2* .XX*: ±1*	NAME: TYPE-C 24P 母座 板上四脚插 双壳 DIP+SMT 脚距2.3 L=9.95 CH=3.4 编带 P.J. NO.: Δ126-223-240002-J4G SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A0 UNIT: mm PAGE: 2/2